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Response  
J. McMillan  
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TECHNOLOGY CENTER 2800

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**  
**EXPEDITED PROCEDURE PURSUANT**  
**TO 37 CFR §1.116 REQUESTED**

**Attn: BOX AF**

Applicants: **T. SATOH et al.**

Application No.: **09/809,181**

Filing Date: **March 16, 2001**

Title: **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD FOR HIGH RELIABILITY AND PRODUCTION YIELD RATE WITH MINIMAL DAMAGE DUE TO APPLICATION OF MECHANICAL STRESS AND THERMAL STRESS (AS AMENDED)**

Art Unit: **2815**

Examiner: **Jose R. Diaz**

**RESPONSE AFTER FINAL**

Assistant Commissioner for Patents  
Washington, D.C. 20231

**September 23, 2002**

Sir:

In response to the final Office Action (Paper No. 14) dated May 21, 2002, the following amendments and remarks are submitted in the above-identified application.

Please amend the above-identified application as follows:

**REMARKS**

Claims 1-10 and 28-36 are pending in this application.

Claims 1-10 and 28-36 have been rejected under 35 U.S.C. §102(b) as being anticipated by, or in the alternative, under 35 U.S.C. §103(a) as being obvious over the